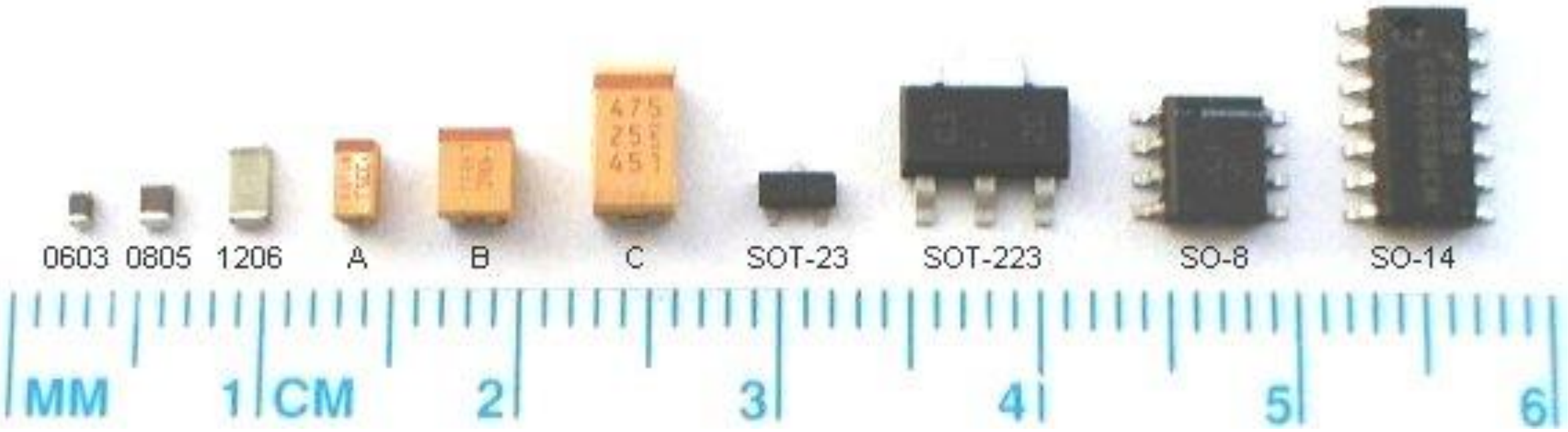
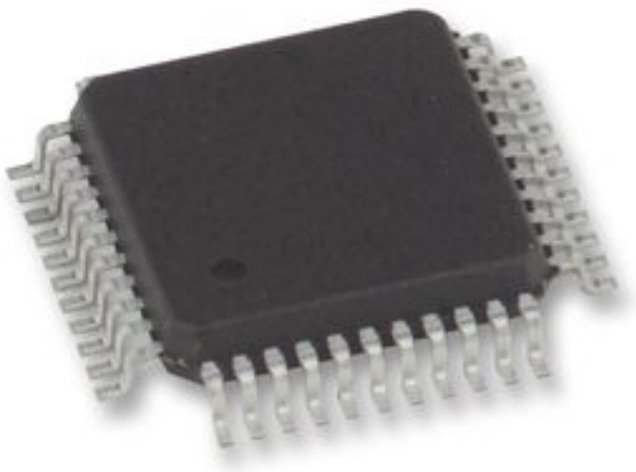
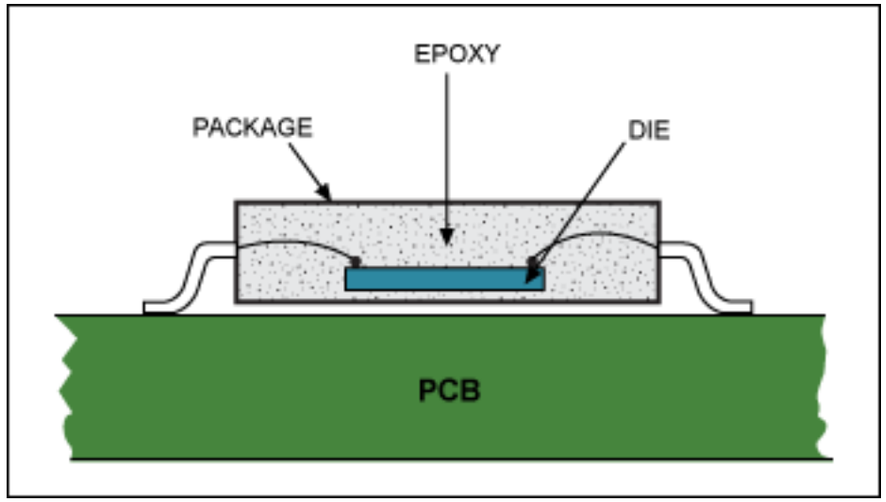
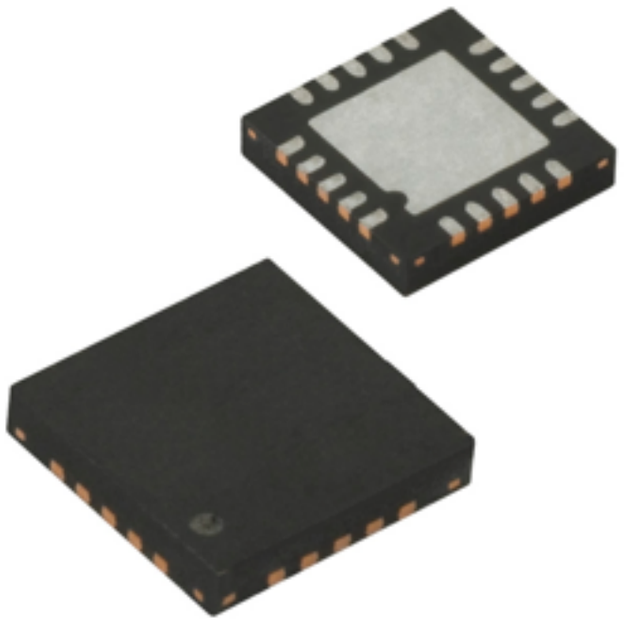

0603
0805
1206
A
B
C
SOT-23
SOT-223
SO-8
SO-14
MM
1
CM
2
3
4
5
6

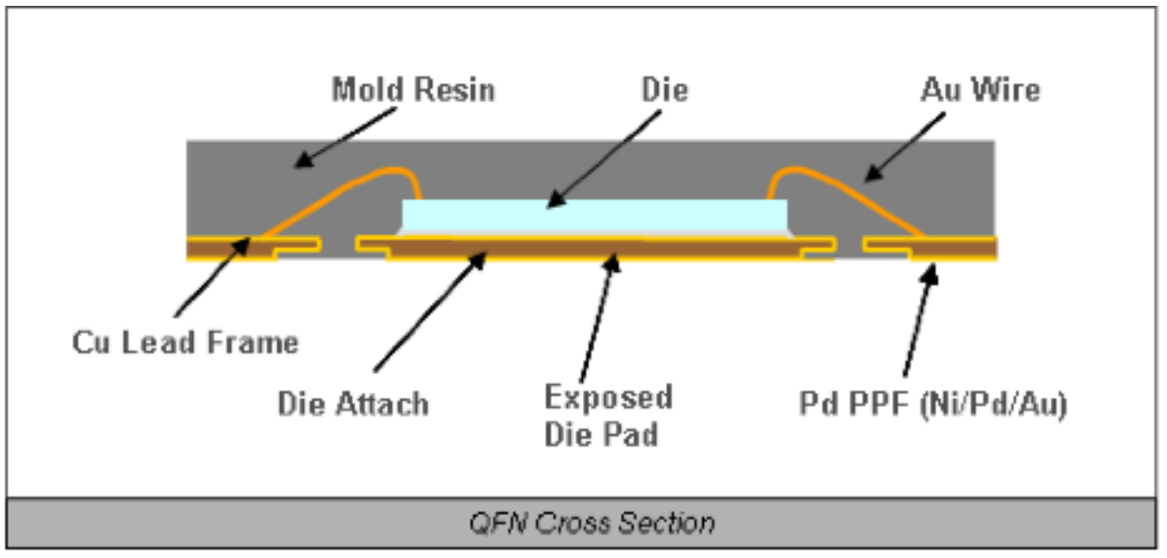


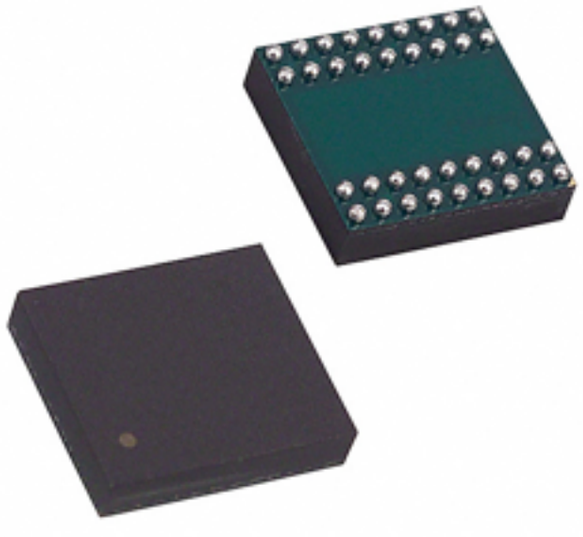
(L)QFP


EPOXY
PACKAGE
DIE
PCB

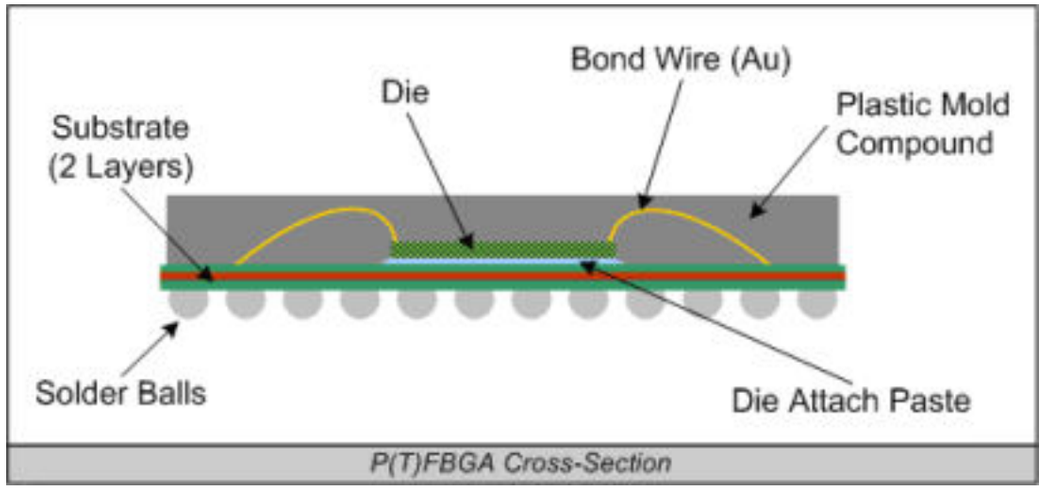


QFN


Mold Resin
Die
Au Wire
Cu Lead Frame
Die Attach
Exposed
Die Pad
Pd PPF (Ni/Pd/Au)
QFN Cross Section



BGA


Bond Wire (Au)
Die
Substrate
(2 Layers)
Plastic Mold
Compound
Solder Balls
Die Attach Paste
P(T)FBGA Cross-Section